

ABSTRACT

WAFER PROCESSING METHOD

A wafer processing method includes: an alignment step of detecting an alignment mark through a sealing material by a visible light imaging unit from the front surface side of the wafer, and detecting a division line to be laser processed based on the alignment mark; a laser processed groove forming step of emitting a laser beam of such a wavelength as to be absorbed in the sealing material along the division lines from the front surface side of the wafer, to form laser processed grooves having a depth corresponding to a finished thickness of the device chips in the sealing material in the cut grooves by ablation processing; and a dividing step of grinding the wafer from a back surface side of the wafer to the finished thickness of the device chips, to expose the laser processed grooves, and dividing the wafer into individual device chips each of which has its front surface and four side surfaces surrounded by the sealing material.

(Figure 4)